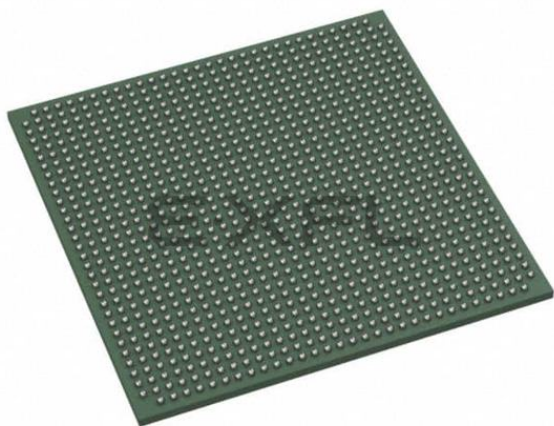




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	6250
Number of Logic Elements/Cells	25000
Total RAM Bits	1966080
Number of I/O	476
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (Tj)
Package / Case	1020-BBGA, FCBGA
Supplier Device Package	1020-OFCBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga25ep1-6ff1020i

Features

■ High Performance FPGA Fabric

- 15K to 115K four input Look-up Tables (LUT4s)
- 139 to 942 I/Os
- 700MHz global clock; 1GHz edge clocks

■ 4 to 32 High Speed SERDES and flexiPCS™ (per Device)

- Performance ranging from 600Mbps to 3.8Gbps
- Excellent Rx jitter tolerance (0.8UI at 3.125Gbps)
- Low Tx jitter (0.25UI typical at 3.125Gbps)
- Built-in Pre-emphasis and equalization
- Low power (typically 105mW per channel)
- Embedded Physical Coding Sublayer (PCS) provides pre-engineered implementation for the following standards:
 - GbE, XAUI, PCI Express, SONET, Serial RapidIO, 1G Fibre Channel, 2G Fibre Channel

■ 2Gbps High Performance PURESPEED™ I/O

- Supports the following performance bandwidths
 - Differential I/O up to 2Gbps DDR (1GHz Clock)
 - Single-ended memory interfaces up to 800Mbps
- 144 Tap programmable Input Delay (INDEL) block on every I/O dynamically aligns data to clock for robust performance
 - Dynamic bit Adaptive Input Logic (AIL) monitoring and control circuitry per pin that automatically ensures proper set-up and hold
 - Dynamic bus: uses control bus from DLL
 - Static per bit
- Electrical standards supported:
 - LVCMOS 3.3/2.5/1.8/1.5/1.2, LVTTTL
 - SSTL 3/2/18 I, II; HSTL 18/15 I, II
 - PCI, PCI-X
 - LVDS, Mini-LVDS, Bus-LVDS, MLVDS, LVPECL, RSDS
- Programmable On Die Termination (ODT)
 - Includes Thevenin Equivalent and low power V_{TT} termination options

■ Memory Intensive FPGA

- sysMEM™ embedded Block RAM

- 1 to 7.8 Mbits memory
- True Dual Port/Pseudo Dual Port/Single Port
- Dedicated FIFO logic for all block RAM
- 500MHz performance
- Additional 240K to 1.8Mbits distributed RAM

■ sysCLOCK™ Network

- Eight analog PLLs per device
 - Frequency range from 15MHz to 1GHz
 - Spread spectrum support
- 12 DLLs per device with direct control of I/O delay
 - Frequency range from 100MHz to 700MHz
- Extensive clocking network
 - 700MHz primary and 325 MHz secondary clocks
 - 1GHz I/O-connected edge clocks
- Precision Clock Divider
 - Phase matched x2 and x4 division of incoming clocks
- Dynamic Clock Select (DCS)
 - Glitch free clock MUX

■ Masked Array for Cost Optimization (MACO™) Blocks

- On-chip structured ASIC Blocks provide pre-engineered IP for low power, low cost system level integration

■ High Performance System Bus

- Ties FPGA elements together with a standard bus framework
 - Connects to peripheral user interfaces for run-time dynamic configuration

■ System Level Support

- IEEE standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer
- IEEE Standard 1532 in-system configuration
- 1.2V and 1.0V operation
- Onboard oscillator for initialization and general use
- Embedded PowerPC microprocessor interface
- Low cost wire-bond and high pin count flip-chip packaging
- Low cost SPI Flash RAM configuration

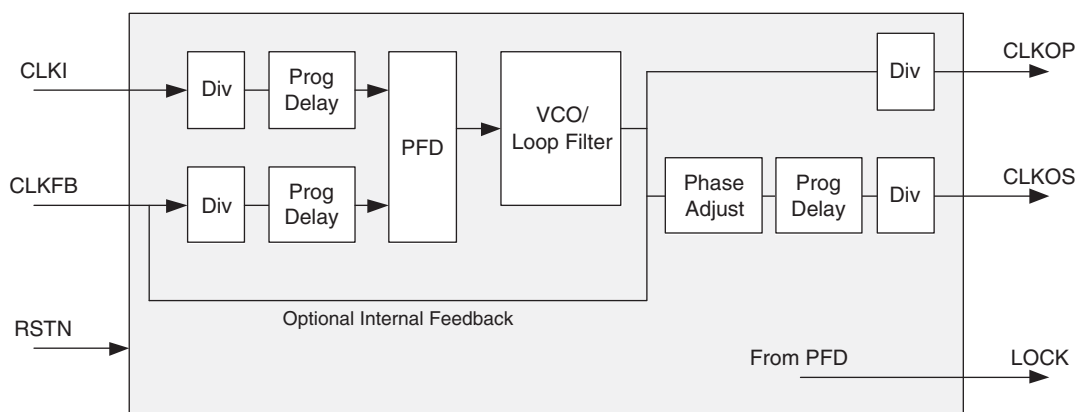
The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically.

The Phase Select block can modify the phase of the clock signal if desired. The Spread Spectrum block supports the modulation of the PLL output frequency. This reduces the peak energy in the fundamental and its harmonics providing for lower EMI (Electro Magnetic Interference).

The sysCLOCK PLL can be configured at power-up and then, if desired, reconfigured dynamically through the serial memory interface bus which connects with the on-chip system bus. For example, the user can select inputs, loop filters, divider setting, delay settings and phase shift settings. The user can also directly access the SMI bus through the routing.

The PLL clock input, from pin or routing, feeds into an input divider. There are four sources of feedback signal to the feedback divider: from the clock net, directly from the voltage controlled oscillator (VCO) output, from the routing or from an external pin. The signal from the input clock divider and the feedback divider are passed through the programmable delay before entering the phase frequency detector (PFD) unit. The output of this PFD is used to control the voltage controlled oscillator. There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-11 shows the sysCLOCK PLL diagram.

Figure 2-11. PLL Diagram



For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Spread Spectrum Clocking (SSC)

The PLL supports spread spectrum clocking to reduce peak EMI by using “down-spread” modulation. The spread spectrum operation will vary the output frequency (at 30KHz to 500KHz) in a range that is between its nominal value, down to a frequency that is a programmable 1%, 2%, or 3% lower than normal.

Digital Locked Loop (DLLs)

In addition to PLLs, the LatticeSC devices have up to 12 DLLs per device. DLLs assist in the management of clocks and strobes. DLLs are well suited to applications where the clock may be stopped or transferring jitter from input to output is important, for example forward clocked interfaces. PLLs are good for applications requiring the lowest output jitter or jitter filtering. All DLL outputs are routed as primary/edge clock sources.

The DLL has two independent clock outputs, CLKOP and CLKOS. These outputs can individually select one of the outputs from the tapped delay line. The CLKOS has optional fine phase shift and divider blocks to allow this output to be further modified, if required. The fine phase shift block allows the CLKOS output to be phase shifted a further 45, 22.5 or 11.25 degrees relative to its normal position. LOCK output signal is asserted when the DLL is locked. The ALU HOLD signal setting allows users to freeze the DLL at its current delay setting.

3. Bottom Side (Banks 4 and 5)

These buffers can support LVCMOS standards up to 3.3V, including PCI33, PCI-X33 and SSTL-33. Differential receivers are provided on all PIO pairs but true HLVDS and RSDS differential drivers are not available. Adaptive input logic is available on PIOs A or C.

Table 2-8 lists the standards supported by each side.

Table 2-8. I/O Standards Supported by Different Banks

Description	Top Side Banks 1	Right Side Banks 2-3	Bottom Side Banks 4-5	Left Side Banks 6-7
I/O Buffer Type	Single-ended, Differential Receiver	Single-ended, Differen- tial Receiver and Driver	Single-ended, Differential Receiver	Single-ended, Differen- tial Receiver and Driver
Output Standards Supported	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II SSTL33_I, II HSTL15_I, II, III ¹ , IV ¹ HSTL18_I, II, III ¹ , IV ¹ SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL ² , GTL+ ²	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II HSTL15_I, III HSTL18_I, II, III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL ² , GTL+ ²	LVTTL LVCMOS33 LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II SSTL33_I, II HSTL15_I, II, III ¹ , IV ¹ HSTL18_I, II, III ¹ , IV ¹ SSTL18D_I, II SSTL25D_I, II SSTL33D_I, II HSTL15D_I, II HSTL18D_I, II PCI33 PCIX15 PCIX33 AGP1X33 AGP2X33 MLVDS/BLVDS GTL ² , GTL+ ²	LVCMOS25 LVCMOS18 LVCMOS15 LVCMOS12 SSTL18_I, II SSTL25_I, II HSTL15_I, III HSTL18_I, II, III PCIX15 SSTL18D_I, II SSTL25D_I, II HSTL15D_I, II HSTL18D_I, II LVDS/RSDS Mini-LVDS MLVDS/BLVDS GTL ² , GTL+ ²
Input Standards Supported	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Clock Inputs	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential	Single-ended, Differential
Differential Output Support via Emulation	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL	LVDS/MLVDS/BLVDS/ LVPECL	MLVDS/BLVDS/ LVPECL
AIL Support	No	Yes	Yes	Yes

1. Input only.

2. Input only. Outputs supported by bussing multiple outputs together.

Supported Standards

The LatticeSC PURESPEED I/O buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS, LVTTL and other standards. The buffers support the LVTTL, LVCMOS 12, 15, 18, 25 and 33 standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, termination resistance, bus maintenance (weak pull-up, weak pull-down, or a bus-keeper latch) and open drain. Other single-ended standards supported include SSTL, HSTL, GTL (input only), GTL+ (input only), PCI33, PCIX33, PCIX15, AGP-1X33 and AGP-2X33. Differential standards supported include LVDS, RSDS, BLVDS, MLVDS, LVPECL, differential SSTL and differential HSTL. Tables 12 and 13 show the I/O standards (together with their supply and reference voltages) supported by the LatticeSC devices. The tables also provide the available internal termination schemes. For further information on utilizing the PURESPEED I/O buffer to support a variety of standards please see details of additional technical documentation at the end of this data sheet.

this allows for easy integration with the rest of the system. These capabilities make the LatticeSC ideal for many multiple power supply and hot-swap applications. The maximum current during hot socketing is 4mA. See Hot Socketing Specifications in Chapter 3 of this data sheet.

Power-Up Requirements

To prevent high power supply and input pin currents, each VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies must have a monotonic ramp up time of 75 ms or less to reach its minimum operating voltage. Apart from VCC and VCC12, which have an additional requirement, and VCCIO and VCCAUX, which also have an additional requirement, the VCC, VCC12, VCCAUX, VCCIO and VCCJ power supplies can ramp up in any order, with no restriction on the time between them. However, the ramp time for each must be 75 ms or less. Configuration of the device will not proceed until the last power supply has reached its minimum operating voltage.

Additional Requirement for VCC and VCC12:

VCC12 must always be higher than VCC. This condition must be maintained at ALL times, including during power-up and power-down. Note that for 1.2V only operation, it is advisable to source both of these supplies from the same power supply.

Additional Requirement for VCCIO and VCCAUX:

If any VCCIOs are 1.2/1.5/1.8V, then VCCAUX MUST be applied before them. If any VCCIO is 1.2/1.5/1.8V and is powered up before VCCAUX, then when VCCAUX is powered up, it may drag VCCIO up with it as it crosses through the VCCIO value. (Note: If the VCCIO supply is capable of sinking current, as well as the more usual sourcing capability, this behavior is eliminated. However, the amount of current that the supply needs to sink is unknown and is likely to be in the hundreds of milliamps range).

Power-Down Requirements

To prevent high power supply and input pin currents, power must be removed monotonically from either VCC or VCCAUX (and must reach the power-down trip point of 0.5V for VCC, 0.95V for VCCAUX) before power is removed monotonically from VCC12, any of the VCCIOs, or VCCJ. Note that VCC12 can be removed at the same time as VCC, but it cannot be removed earlier. In many applications, VCC and VCC12 will be sourced from the same power supply and so will be removed together. For systems where disturbance of the user pins is a don't care condition, the power supplies can be removed in any order as long as they power down monotonically within 200ms of each other.

Additionally, if any banks have VCCIO=3.3V nominal (potentially banks 1, 4, 5) then VCCIO for those banks must not be lower than VCCAUX during power-down. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern here.

Note: The SERDES power supplies are NOT included in these requirements and have no specific sequencing requirements. However, when using the SERDES with VDDIB or VDDOB that is greater than 1.2V (1.5V nominal for example), the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in the ramp-up times of power supplies and voltage regulators is not a concern here.

SERDES Power Supply Sequencing Requirements

When using the SERDES with 1.5V VDDIB or VDDOB supplies, the SERDES should not be left in a steady state condition with the 1.5V power applied and the 1.2V power not applied. Both the 1.2V and the 1.5V power should be applied to the SERDES at nominally the same time. The normal variation in ramp-up times of power supplies and voltage regulators is not a concern.

Additional Requirement for SERDES Power Supply

All VCC12 pins need to be connected on all devices independent of functionality used on the device. This analog supply is used by both the RX and TX portions of the SERDES and is used to control the core SERDES logic regardless of the SERDES being used in the design. VDDIB and VDDOB are used as supplies for the terminations on the CML input and output buffers. If a particular channel is not used, these can be UNCONNECTED (floating).

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

MLVDS

The LatticeSC devices support the MLVDS standard. This industry standard is emulated using controlled impedance complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. MLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-1 is one possible solution for bi-directional multi-point differential signals.

Figure 3-1. MLVDS Multi-Point Output Example

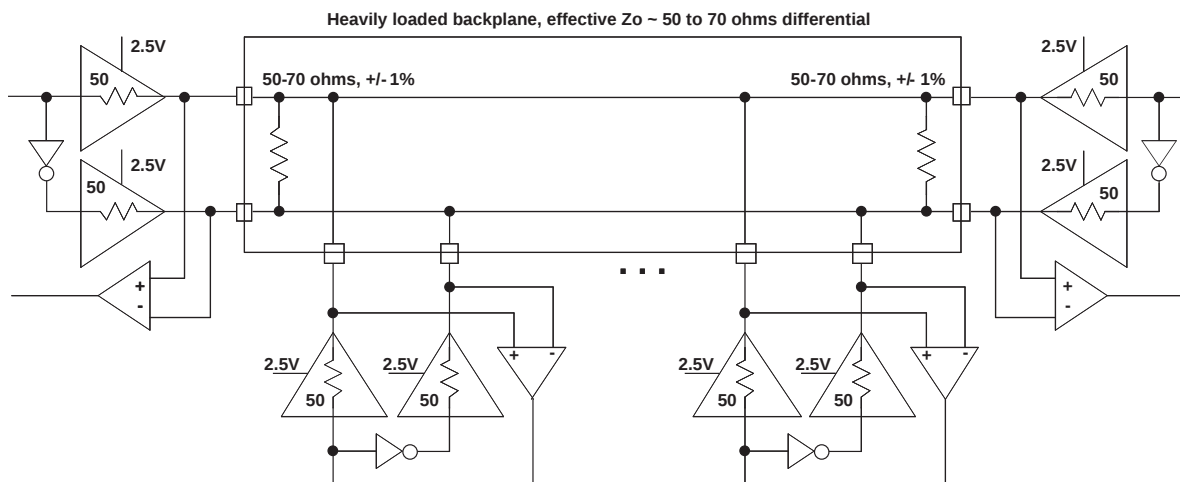


Table 3-1. MLVDS DC Conditions¹

Over Recommended Operating Conditions

Symbol	Description	Nominal		Units
		Z _o = 50	Z _o = 70	
Z _{OUT}	Output impedance	50	50	ohm
R _{TLEFT}	Left end termination	50	70	ohm
R _{TRIGHT}	Right end termination	50	70	ohm
V _{OH}	Output high voltage	1.50	1.575	V
V _{OL}	Output low voltage	1.00	0.925	V
V _{OD}	Output differential voltage	0.50	0.65	V
V _{CM}	Output common mode voltage	1.25	1.25	V
I _{DC}	DC output current	20.0	18.5	mA

1. For input buffer, see LVDS table.

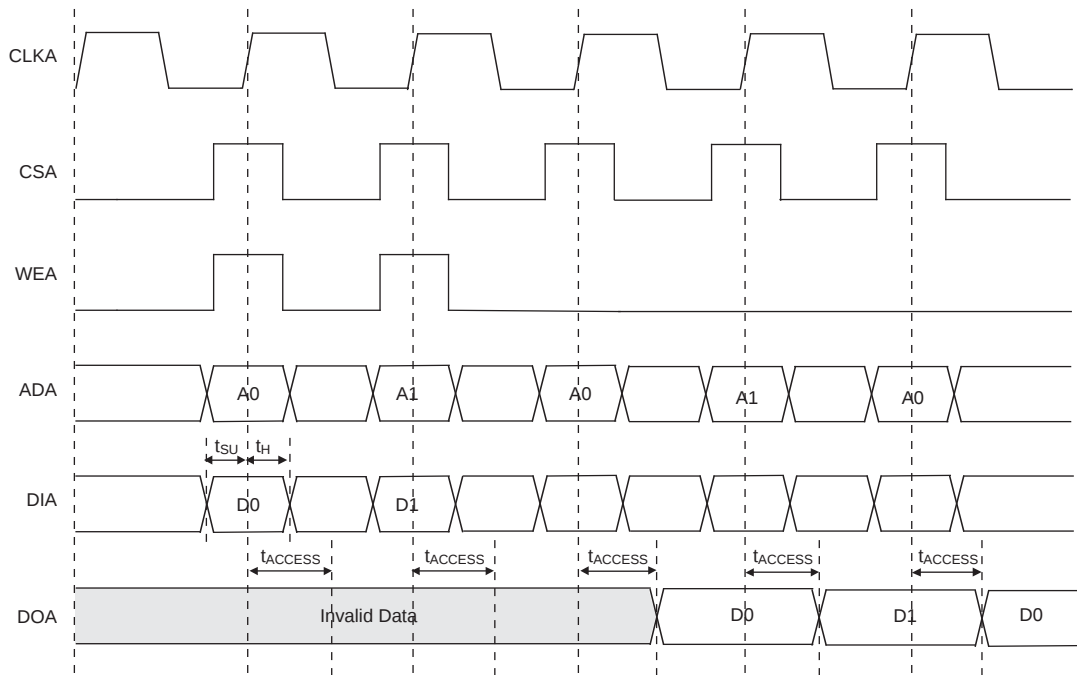
LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
GTLPLUS15	GTLPLUS15	-0.013	-0.017	0.012	0.004	0.037	0.024	ns
GTL12	GTL12	-0.063	-0.071	-0.007	-0.048	0.056	-0.032	ns
Output Adjusters								
LVDS	LVDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
RSDS	RSDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
BLVDS25	BLVDS	-0.129	0.05	-0.136	0.069	-0.136	0.083	ns
MLVDS25	MLVDS	-0.059	0.059	-0.057	0.096	-0.054	0.133	ns
LVPECL33	LVPECL	-0.334	-0.181	-0.325	-1.389	-0.315	-2.598	ns
HSTL18_I	HSTL_18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18_II	HSTL_18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL18D_I	Differential HSTL 18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18D_II	Differential HSTL 18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL15_I	HSTL_15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15_II	HSTL_15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
HSTL15D_I	Differential HSTL 15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15D_II	Differential HSTL 15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
SSTL33_I	SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33_II	SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL33D_I	Differential SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33D_II	Differential SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL25_I	SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25_II	SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL25D_I	Differential SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25D_II	Differential SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL18_I	SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18_II	SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
SSTL18D_I	Differential SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18D_II	Differential SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
LVTTTL33_8mA	LVTTTL 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVTTTL33_16mA	LVTTTL 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVTTTL33_24mA	LVTTTL 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVC MOS33_24mA	LVC MOS 3.3 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	-0.174	0.004	-0.195	0.002	-0.215	0	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0	0	0	0	0	0	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.094	-0.025	0.107	0.096	0.12	0.216	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.145	-0.054	0.162	0.063	0.181	0.179	ns
LVC MOS25_OD	LVC MOS 2.5 open drain	0.073	-0.125	0.081	-0.081	0.091	-0.09	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	-0.278	-0.099	-0.312	-0.115	-0.345	-0.131	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	-0.073	-0.078	-0.078	-0.084	-0.083	-0.089	ns

EBR Memory Timing Diagrams

Figure 3-6. Read Mode



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-7. Read Mode with Input Registers Only

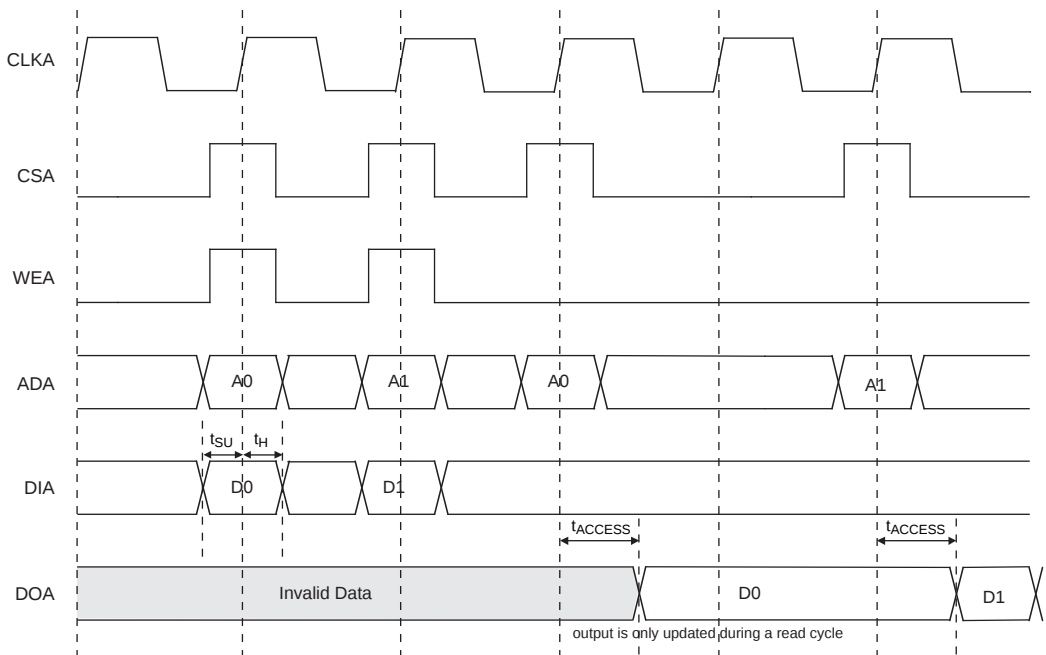


Figure 3-8. Read Mode with Input and Output Registers

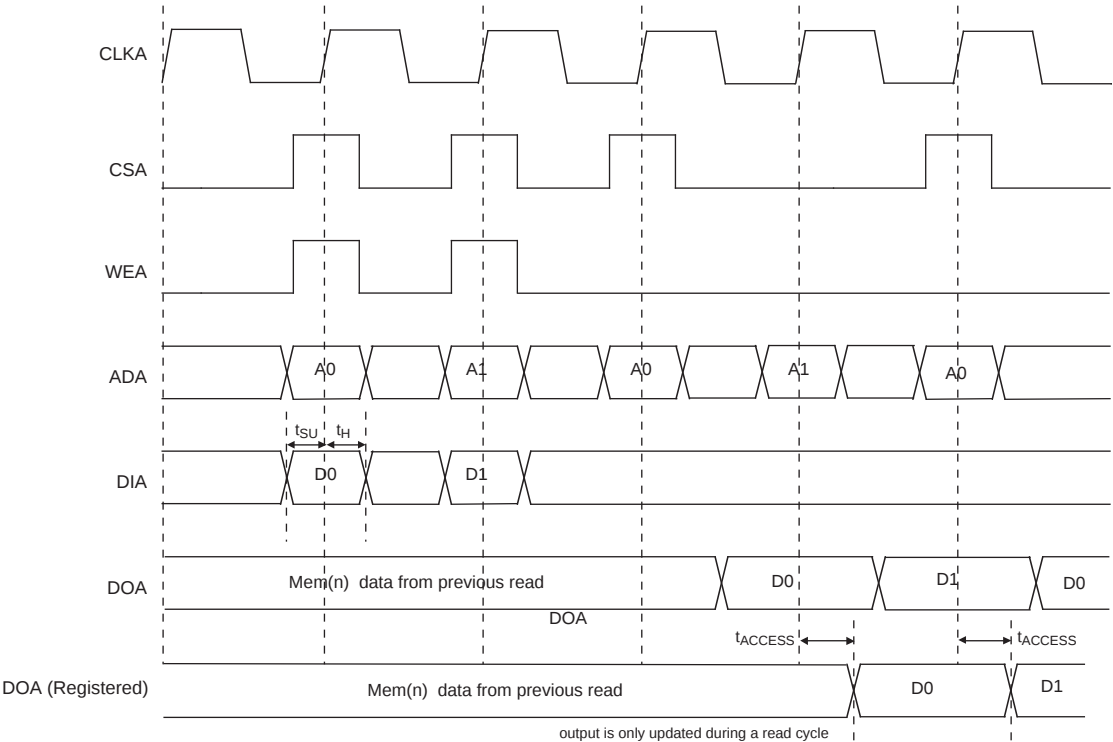
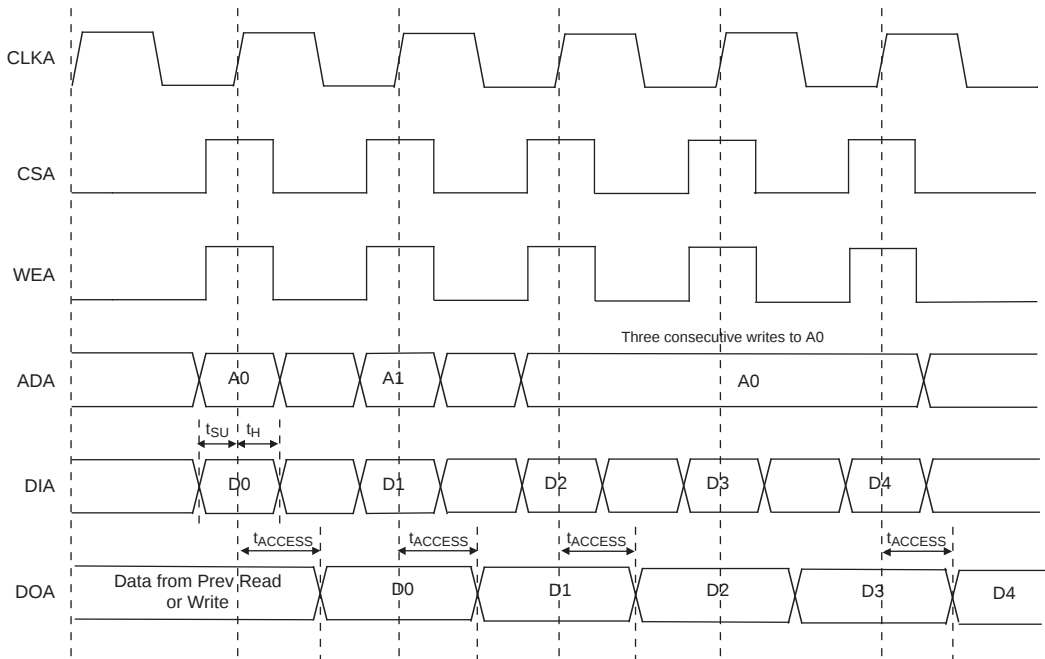
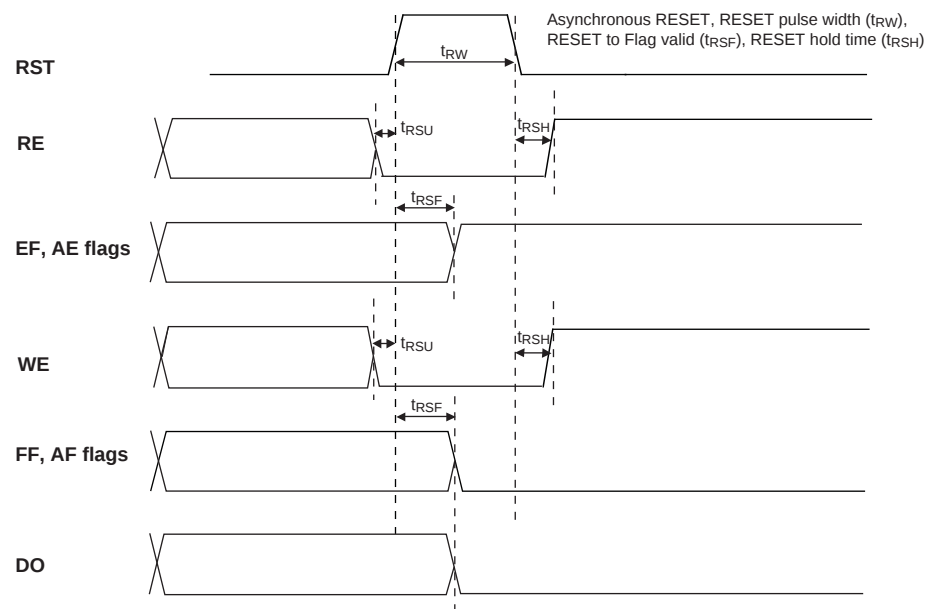


Figure 3-9. Write Through (SP Read/Write On Port A, Input Registers Only)



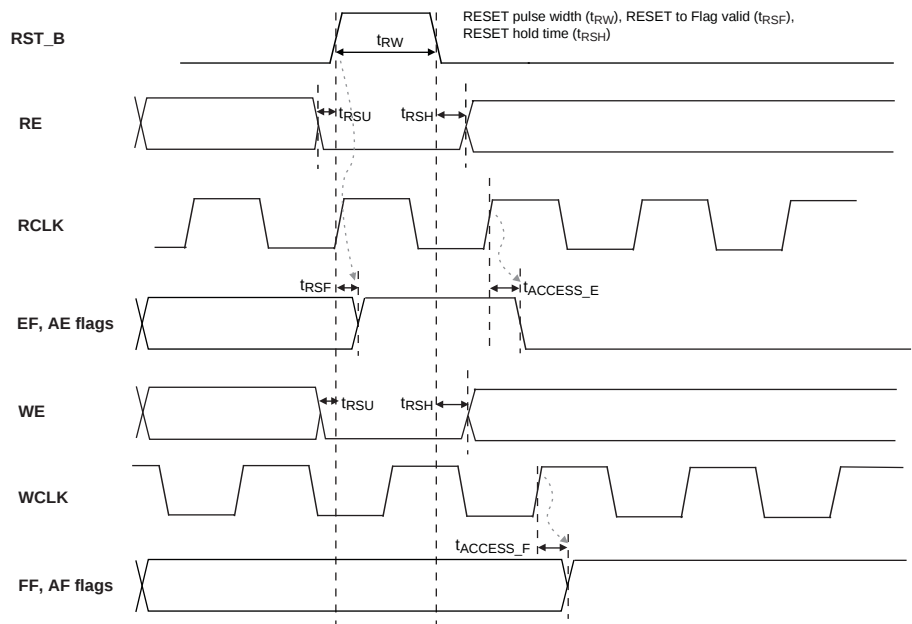
Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

Figure 3-10. FIFO Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

Figure 3-11. Read Pointer Reset Waveform



Note: RE and WE must be deactivated t_{RSU} before the Positive FIFO reset edge and enabled t_{RSH} after the FIFO reset negative edge.

LatticeSC/M sysCONFIG Port Timing (Continued)

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
sysCONFIG Asynchronous Peripheral Configuration Mode				
t_{WRAP}	WRN, CS0N and CS1 Pulse Width	5	-	ns
t_{SAP}	D[7:0] Setup Time	1.5	-	ns
t_{RDYAP}	RDY Delay	—	8	ns
t_{BAP}	RDY Low	1	8	CCLK periods
t_{WR2AP}	Earliest WRN After RDY Goes High	0	—	ns
t_{DENAP}	RDN to D[7:0] Enable/Disable	—	7.5	ns
t_{DAP}	CCLK to DOUT	—	7.5	ns
sysCONFIG Slave Serial Configuration Mode				
t_{SSS}	DIN Setup Time	5.2	—	ns
t_{HSS}	DIN Hold Time	0	—	ns
t_{CHSS}	CCLK High Time	3.75	—	ns
t_{CLSS}	CCLK Low Time	3.75	—	ns
f_{CSS}	CCLK Frequency	—	150	MHz
t_{DSS}	CCLK to DOUT	—	7.5	ns
sysCONFIG Slave Parallel Configuration Mode				
t_{S1SP}	CS0N, CS1, WRN Setup Time	5.2	—	ns
t_{H1SP}	CS0N, CS1, WRN Hold Time	0	—	ns
t_{S2SP}	D[7:0] Setup Time	5.2	—	ns
t_{H2SP}	D[7:0] Hold Time	0	—	ns
t_{CHSP}	CCLK High Time	3.75	—	ns
t_{CL}	CCLK Low Time	3.75	—	ns
f_{CSP}	CCLK Frequency	—	150	MHz

sysCONFIG MPI Port

Parameter	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{MPICTRL_SET}$	MPI Control (MPCSTRBN, MPCWRN, MPCCLK, etc.) to MPCCLK Setup Time	4.9	—	5.2	—	5.5	—	ns
t_{MPIADR_SET}	MPI Address to MPCCLK Setup Time	3.9	—	4.2	—	4.5	—	ns
t_{MPIDAT_SET}	MPI Write Data to MPCCLK Setup Time	4.9	—	5.2	—	5.5	—	ns
$t_{MPIDPAR_SET}$	MPI Write Parity Data to MPCCLK Setup Time	3.9	—	4.2	—	4.5	—	ns
t_{MPI_HLD}	All Hold Times	0	—	0	—	0	—	ns
$t_{MPICTRL_DEL}$	MPCCLK to MPI Control (MPCTA, MPC-TEA, MPCRETRY)	—	5.6	—	6.7	—	8.7	ns
t_{MPIDAT_DEL}	MPCCLK to MPI Data	—	5.6	—	6.7	—	8.7	ns
$t_{MPIDPAR_DEL}$	MPCCLK to MPI Parity Data	—	4.9	—	5.7	—	7.7	ns
$f_{MPI_CLK_FRQ}$	MPCCLK Frequency	—	100	—	83	—	66	MHz

LFSC/M15 Logic Signal Connections: 256 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
F14	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
E15	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
E14	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
D9	VCCJ	-	
C16	TDO	-	TDO
B15	TMS	-	
B16	TCK	-	
E13	TDI	-	
C14	PROGRAMN	1	
C15	CCLK	1	
A15	PT43D	1	HDC/SI
A14	PT43C	1	LDCN/SCS
B14	PT41A	1	CS1
E12	PT39B	1	CS0N
D13	PT39A	1	RDN
D12	PT37D	1	WRN
E10	PT37C	1	D7
C11	PT37B	1	D6
D10	PT37A	1	D5
A13	PT36D	1	D4
B12	PT36C	1	D3
A12	PT35B	1	D2
C12	PT35A	1	D1
A11	PT33B	1	D0
B11	PT33A	1	QOUT/CEON
E9	PT32D	1	VREF2_1
E8	PT32B	1	DOUT
D8	PT28C	1	BUSYN/RCLK/SCK
A10	PT27B	1	PCLKC1_0
C10	PT27A	1	PCLKT1_0
E7	PT21C	1	VREF1_1
C9	A_VDDIB3_L	-	
A9	A_HDINP3_L	-	PCS 360 CH 3 IN P
B9	A_HDINN3_L	-	PCS 360 CH 3 IN N
A8	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B8	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
C8	A_VDDOB3_L	-	
B7	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
C7	A_VDDOB2_L	-	
A7	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
B6	A_HDINN2_L	-	PCS 360 CH 2 IN N
A6	A_HDINP2_L	-	PCS 360 CH 2 IN P
C6	A_VDDIB2_L	-	

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA^{1, 2} (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB10	VCC	-		VCC	-	
AB21	VCC	-		VCC	-	
J10	VCC	-		VCC	-	
J21	VCC	-		VCC	-	
K10	VCC	-		VCC	-	
K11	VCC	-		VCC	-	
K12	VCC	-		VCC	-	
K13	VCC	-		VCC	-	
K14	VCC	-		VCC	-	
K17	VCC	-		VCC	-	
K18	VCC	-		VCC	-	
K19	VCC	-		VCC	-	
K20	VCC	-		VCC	-	
K21	VCC	-		VCC	-	
K22	VCC	-		VCC	-	
K9	VCC	-		VCC	-	
L10	VCC	-		VCC	-	
L21	VCC	-		VCC	-	
M10	VCC	-		VCC	-	
M21	VCC	-		VCC	-	
N10	VCC	-		VCC	-	
N21	VCC	-		VCC	-	
P10	VCC	-		VCC	-	
P21	VCC	-		VCC	-	
U10	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
V10	VCC	-		VCC	-	
V21	VCC	-		VCC	-	
W10	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
Y10	VCC	-		VCC	-	
Y21	VCC	-		VCC	-	
H11	VCCAUX	-		VCCAUX	-	
H12	VCCAUX	-		VCCAUX	-	
H19	VCCAUX	-		VCCAUX	-	
H20	VCCAUX	-		VCCAUX	-	
M23	VCCAUX	-		VCCAUX	-	
M24	VCCAUX	-		VCCAUX	-	
N23	VCCAUX	-		VCCAUX	-	
N24	VCCAUX	-		VCCAUX	-	
U23	VCCAUX	-		VCCAUX	-	
U24	VCCAUX	-		VCCAUX	-	
V23	VCCAUX	-		VCCAUX	-	
V24	VCCAUX	-		VCCAUX	-	
W23	VCCAUX	-		VCCAUX	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
B1	GND	-		GND	-	
B32	GND	-		GND	-	
C11	GND	-		GND	-	
C12	GND	-		GND	-	
C16	GND	-		GND	-	
C21	GND	-		GND	-	
C22	GND	-		GND	-	
C24	GND	-		GND	-	
C25	GND	-		GND	-	
C26	GND	-		GND	-	
C27	GND	-		GND	-	
C29	GND	-		GND	-	
C3	GND	-		GND	-	
C30	GND	-		GND	-	
C4	GND	-		GND	-	
C6	GND	-		GND	-	
C7	GND	-		GND	-	
C8	GND	-		GND	-	
C9	GND	-		GND	-	
D17	GND	-		GND	-	
F18	GND	-		GND	-	
F3	GND	-		GND	-	
F30	GND	-		GND	-	
F9	GND	-		GND	-	
G15	GND	-		GND	-	
G24	GND	-		GND	-	
G29	GND	-		GND	-	
G3	GND	-		GND	-	
J14	GND	-		GND	-	
J22	GND	-		GND	-	
J26	GND	-		GND	-	
J6	GND	-		GND	-	
K11	GND	-		GND	-	
K19	GND	-		GND	-	
K30	GND	-		GND	-	
K4	GND	-		GND	-	
L23	GND	-		GND	-	
L9	GND	-		GND	-	
M13	GND	-		GND	-	
M15	GND	-		GND	-	
M18	GND	-		GND	-	
M20	GND	-		GND	-	
M27	GND	-		GND	-	
M7	GND	-		GND	-	
N12	GND	-		GND	-	
N14	GND	-		GND	-	
N19	GND	-		GND	-	
N21	GND	-		GND	-	
N29	GND	-		GND	-	
N3	GND	-		GND	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G27	A_REFCLKP_L	-		A_REFCLKP_L	-	
H27	A_REFCLKN_L	-		A_REFCLKN_L	-	
H25	VCC12	-		VCC12	-	
H26	RESP_ULC	-		RESP_ULC	-	
B33	RESETN	1		RESETN	1	
C34	TSALLN	1		TSALLN	1	
D34	DONE	1		DONE	1	
C33	INITN	1		INITN	1	
J27	M0	1		M0	1	
K27	M1	1		M1	1	
M26	M2	1		M2	1	
L26	M3	1		M3	1	
F30	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
G30	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
H28	PL16C	7		PL16C	7	
J28	PL16D	7		PL16D	7	
F31	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G31	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N25	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P25	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
D33	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
E33	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
H29	PL18C	7		PL18C	7	
J29	PL18D	7	VREF2_7	PL18D	7	VREF2_7
F32	PL21A	7		PL20A	7	
G32	PL21B	7		PL20B	7	
P26	PL21C	7		PL20C	7	
N26	PL21D	7		PL20D	7	
H30	PL22A	7		PL21A	7	
J30	PL22B	7		PL21B	7	
L28	PL22C	7		PL21C	7	
M28	PL22D	7		PL21D	7	
J31	PL23A	7		PL29A	7	
K31	PL23B	7		PL29B	7	
L27	PL23C	7	VREF1_7	PL29C	7	VREF1_7
M27	PL23D	7	DIFFR_7	PL29D	7	DIFFR_7
J32	PL25A	7		PL31A	7	
K32	PL25B	7		PL31B	7	
L29	PL25C	7		PL31C	7	
M29	PL25D	7		PL31D	7	
H33	PL26A	7		PL33A	7	
J33	PL26B	7		PL33B	7	
N27	PL26C	7		PL33C	7	
P27	PL26D	7		PL33D	7	
K33	PL27A	7		PL35A	7	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
Y4	PR48B	3		PR63B	3	
W4	PR48A	3		PR63A	3	
W11	PR47D	3		PR60D	3	
V11	PR47C	3		PR60C	3	
W2	PR47B	3		PR60B	3	
V2	PR47A	3		PR60A	3	
W9	PR45D	3		PR57D	3	
V9	PR45C	3		PR57C	3	
V1	PR45B	3		PR57B	3	
U1	PR45A	3		PR57A	3	
W10	PR44D	3		PR56D	3	
V10	PR44C	3		PR56C	3	
U2	PR44B	3		PR56B	3	
T2	PR44A	3		PR56A	3	
Y8	PR43D	3		PR55D	3	
W8	PR43C	3	VREF1_3	PR55C	3	VREF1_3
W5	PR43B	3		PR55B	3	
V5	PR43A	3		PR55A	3	
V7	PR40D	3	PCLKC3_2	PR52D	3	PCLKC3_2
U7	PR40C	3	PCLKT3_2	PR52C	3	PCLKT3_2
T1	PR40B	3		PR52B	3	
R1	PR40A	3		PR52A	3	
V8	PR39D	3	PCLKC3_3	PR51D	3	PCLKC3_3
U8	PR39C	3	PCLKT3_3	PR51C	3	PCLKT3_3
U5	PR39B	3		PR51B	3	
T5	PR39A	3		PR51A	3	
V6	PR38D	3	PCLKC3_1	PR50D	3	PCLKC3_1
U6	PR38C	3	PCLKT3_1	PR50C	3	PCLKT3_1
T4	PR38B	3	PCLKC3_0	PR50B	3	PCLKC3_0
T3	PR38A	3	PCLKT3_0	PR50A	3	PCLKT3_0
U9	PR36D	2	PCLKC2_2	PR48D	2	PCLKC2_2
T9	PR36C	2	PCLKT2_2	PR48C	2	PCLKT2_2
R2	PR36B	2	PCLKC2_0	PR48B	2	PCLKC2_0
P2	PR36A	2	PCLKT2_0	PR48A	2	PCLKT2_0
T11	PR35D	2	PCLKC2_3	PR47D	2	PCLKC2_3
U11	PR35C	2	PCLKT2_3	PR47C	2	PCLKT2_3
R4	PR35B	2	PCLKC2_1	PR47B	2	PCLKC2_1
R3	PR35A	2	PCLKT2_1	PR47A	2	PCLKT2_1
T8	PR34D	2		PR46D	2	
R8	PR34C	2		PR46C	2	
P1	PR34B	2		PR46B	2	
N1	PR34A	2		PR46A	2	
R6	PR31D	2		PR43D	2	
P6	PR31C	2		PR43C	2	
M1	PR31B	2		PR43B	2	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
W13	VCCAUX	-		VCCAUX	-	
W22	VCCAUX	-		VCCAUX	-	
Y21	GND	-		GND	-	
Y25	GND	-		GND	-	
C18	VCCIO1	-		VCCIO1	-	
D17	VCCIO1	-		VCCIO1	-	
F16	VCCIO1	-		VCCIO1	-	
G19	VCCIO1	-		VCCIO1	-	
J20	VCCIO1	-		VCCIO1	-	
K12	VCCIO1	-		VCCIO1	-	
K15	VCCIO1	-		VCCIO1	-	
L23	VCCIO1	-		VCCIO1	-	
Y9	GND	-		GND	-	
J9	VCCIO1	-		VCCIO1	-	
E3	VCCIO2	-		VCCIO2	-	
G6	VCCIO2	-		VCCIO2	-	
H4	VCCIO2	-		VCCIO2	-	
K7	VCCIO2	-		VCCIO2	-	
L3	VCCIO2	-		VCCIO2	-	
M11	VCCIO2	-		VCCIO2	-	
N6	VCCIO2	-		VCCIO2	-	
P4	VCCIO2	-		VCCIO2	-	
R9	VCCIO2	-		VCCIO2	-	
AA3	VCCIO3	-		VCCIO3	-	
AB7	VCCIO3	-		VCCIO3	-	
AC10	VCCIO3	-		VCCIO3	-	
AD4	VCCIO3	-		VCCIO3	-	
AE6	VCCIO3	-		VCCIO3	-	
AG3	VCCIO3	-		VCCIO3	-	
AK4	VCCIO3	-		VCCIO3	-	
T7	VCCIO3	-		VCCIO3	-	
U3	VCCIO3	-		VCCIO3	-	
V4	VCCIO3	-		VCCIO3	-	
W6	VCCIO3	-		VCCIO3	-	
Y10	VCCIO3	-		VCCIO3	-	
AD12	VCCIO4	-		VCCIO4	-	
AF15	VCCIO4	-		VCCIO4	-	
AF9	VCCIO4	-		VCCIO4	-	
AH10	VCCIO4	-		VCCIO4	-	
AH16	VCCIO4	-		VCCIO4	-	
AJ13	VCCIO4	-		VCCIO4	-	
AJ7	VCCIO4	-		VCCIO4	-	
AL14	VCCIO4	-		VCCIO4	-	
AL8	VCCIO4	-		VCCIO4	-	
AM11	VCCIO4	-		VCCIO4	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AC19	VTT_5	5		VTT_5	5	
AC20	VTT_5	5		VTT_5	5	
AD22	VTT_5	5		VTT_5	5	
AB24	VTT_6	6		VTT_6	6	
W23	VTT_6	6		VTT_6	6	
Y23	VTT_6	6		VTT_6	6	
N24	VTT_7	7		VTT_7	7	
R23	VTT_7	7		VTT_7	7	
T23	VTT_7	7		VTT_7	7	
M12	VDDAX25_R	-		VDDAX25_R	-	
M23	VDDAX25_L	-		VDDAX25_L	-	
Y16	GND	-		GND	-	
Y14	GND	-		GND	-	
N21	VCC12	-		VCC12	-	
P22	VCC12	-		VCC12	-	
AA22	VCC12	-		VCC12	-	
AB21	VCC12	-		VCC12	-	
AB14	VCC12	-		VCC12	-	
AA13	VCC12	-		VCC12	-	
P13	VCC12	-		VCC12	-	
N14	VCC12	-		VCC12	-	
G26	NC	-		NC	-	
G9	NC	-		NC	-	
J12	NC	-		NC	-	
H12	NC	-		NC	-	
H23	NC	-		NC	-	
J23	NC	-		NC	-	

1. Differential pair grouping within a PCI is A (True) and B (complement) and C (True) and D (Complement).

2. The LatticeSC/M40 and LatticeSC/M80 in an 1152-pin package support a 32-bit MPI interface.

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AP20	PB61B	5	
AH21	PB61C	5	
AH20	PB61D	5	
AM20	PB63A	5	
AM19	PB63B	5	
AJ21	PB63C	5	
AJ20	PB63D	5	
AK19	PB66A	5	
AK18	PB66B	5	
AE18	PB66C	5	
AD18	PB66D	5	
AN19	PB69A	5	
AN18	PB69B	5	
AG18	PB69C	5	
AF18	PB69D	5	
AP19	PB71A	5	
AP18	PB71B	5	
AJ18	PB71C	5	
AH18	PB71D	5	
AP17	PB73A	4	
AP16	PB73B	4	
AJ17	PB73C	4	
AH17	PB73D	4	
AN17	PB75A	4	
AN16	PB75B	4	
AE17	PB75C	4	
AD17	PB75D	4	
AK17	PB78A	4	
AK16	PB78B	4	
AG17	PB78C	4	
AF17	PB78D	4	
AM16	PB81A	4	
AM15	PB81B	4	
AJ15	PB81C	4	
AJ14	PB81D	4	
AL16	PB83A	4	
AL15	PB83B	4	
AG16	PB83C	4	
AF16	PB83D	4	
AP15	PB86A	4	
AP14	PB86B	4	
AH15	PB86C	4	
AH14	PB86D	4	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H18	PT77C	1	LDCN/SCS	PT93C	1	LDCN/SCS
F18	PT77B	1	D8/MPI_DATA8	PT93B	1	D8/MPI_DATA8
E18	PT77A	1	CS1/MPI_CS1	PT93A	1	CS1/MPI_CS1
H19	PT75D	1	D9/MPI_DATA9	PT90D	1	D9/MPI_DATA9
G19	PT75C	1	D10/MPI_DATA10	PT90C	1	D10/MPI_DATA10
D19	PT75B	1	CS0N/MPI_CS0N	PT90B	1	CS0N/MPI_CS0N
D18	PT75A	1	RDN/MPI_STRB_N	PT90A	1	RDN/MPI_STRB_N
J20	PT74D	1	WRN/MPI_WR_N	PT89D	1	WRN/MPI_WR_N
K20	PT74C	1	D7/MPI_DATA7	PT89C	1	D7/MPI_DATA7
E19	PT74B	1	D6/MPI_DATA6	PT89B	1	D6/MPI_DATA6
F19	PT74A	1	D5/MPI_DATA5	PT89A	1	D5/MPI_DATA5
K18	PT73D	1	D4/MPI_DATA4	PT87D	1	D4/MPI_DATA4
J18	PT73C	1	D3/MPI_DATA3	PT87C	1	D3/MPI_DATA3
A19	PT73B	1	D2/MPI_DATA2	PT87B	1	D2/MPI_DATA2
B19	PT73A	1	D1/MPI_DATA1	PT87A	1	D1/MPI_DATA1
H17	PT71D	1	D16/PCLKC1_3/MPI_DATA16	PT86D	1	D16/PCLKC1_3/MPI_DATA16
J17	PT71C	1	D17/PCLKT1_3/MPI_DATA17	PT86C	1	D17/PCLKT1_3/MPI_DATA17
B20	PT71B	1	D0/MPI_DATA0	PT86B	1	D0/MPI_DATA0
C20	PT71A	1	QOUT/CEON	PT86A	1	QOUT/CEON
M20	PT70D	1	VREF2_1	PT83D	1	VREF2_1
L20	PT70C	1	D18/MPI_DATA18	PT83C	1	D18/MPI_DATA18
F20	PT70B	1	DOUT	PT83B	1	DOUT
G20	PT70A	1	MCA_DONE_IN	PT83A	1	MCA_DONE_IN
K19	PT69D	1	D19/PCLKC1_2/MPI_DATA19	PT81D	1	D19/PCLKC1_2/MPI_DATA19
J19	PT69C	1	D20/PCLKT1_2/MPI_DATA20	PT81C	1	D20/PCLKT1_2/MPI_DATA20
D20	PT69B	1	MCA_CLK_P1_OUT	PT81B	1	MCA_CLK_P1_OUT
E20	PT69A	1	MCA_CLK_P1_IN	PT81A	1	MCA_CLK_P1_IN
H21	PT67D	1	D21/PCLKC1_1/MPI_DATA21	PT78D	1	D21/PCLKC1_1/MPI_DATA21
G21	PT67C	1	D22/PCLKT1_1/MPI_DATA22	PT78C	1	D22/PCLKT1_1/MPI_DATA22
B21	PT67B	1	MCA_CLK_P2_OUT	PT78B	1	MCA_CLK_P2_OUT
C21	PT67A	1	MCA_CLK_P2_IN	PT78A	1	MCA_CLK_P2_IN
M21	PT66D	1	MCA_DONE_OUT	PT75D	1	MCA_DONE_OUT
L21	PT66C	1	BUSYN/RCLK/SCK	PT75C	1	BUSYN/RCLK/SCK
A21	PT66B	1	DP0/MPI_PAR0	PT75B	1	DP0/MPI_PAR0
A20	PT66A	1	MPI_TA	PT75A	1	MPI_TA
J21	PT65D	1	D23/MPI_DATA23	PT73D	1	D23/MPI_DATA23
K21	PT65C	1	DP2/MPI_PAR2	PT73C	1	DP2/MPI_PAR2
E21	PT65B	1	PCLKC1_0	PT73B	1	PCLKC1_0
F21	PT65A	1	PCLKT1_0/MPI_CLK	PT73A	1	PCLKT1_0/MPI_CLK
G22	PT63D	1	DP3/PCLKC1_4/MPI_PAR3	PT71D	1	DP3/PCLKC1_4/MPI_PAR3
H22	PT63C	1	D24/PCLKT1_4/MPI_DATA24	PT71C	1	D24/PCLKT1_4/MPI_DATA24
A23	PT63B	1	MPI_RETRY	PT71B	1	MPI_RETRY
A22	PT63A	1	A0/MPI_ADDR14	PT71A	1	A0/MPI_ADDR14
L22	PT61D	1	A1/MPI_ADDR15	PT69D	1	A1/MPI_ADDR15
M22	PT61C	1	A2/MPI_ADDR16	PT69C	1	A2/MPI_ADDR16

Date	Version	Section	Change Summary
March 2007 (cont.)	01.5 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Internal Timing Parameters with ispLEVER 6.1 SP1 results.
			Updated t_{FDEL} and t_{CDEL} specifications.
			Updated LatticeSC Family Timing Adders with ispLEVER 6.1 SP1 results.
			Updated PLL specifications to expand frequency range down to 2 MHz and break out jitter for the different ranges.
			Added footnote to sysCLOCK PLL Timing table specifying the conditions for the jitter measurements.
			Added t_{DLL} specification to sysCLOCK DLL Timing table.
			Added footnote to sysCLOCK DLL Timing table specifying the conditions for the jitter measurements.
			Added sysCONFIG Master Parallel Configuration Mode and sysCONFIG SPI Port to LatticeSC sysCONFIG Port Timing table.
		Pin Information	Updated Pin Information Summary with SC40 information.
			Updated LFSC25 Logic Signal Connections: FF1020 with SC40 information.
			Updated LFSC80 Logic Signal Connections: FC1152 with SC40 information.
August 2007	01.6	General	Changed references of "HDC" to "HDC/SI".
			Changed references of "LDCN" to "LDCN/SCS".
			Changed references of "BUSYN/RCLK" to "BUSYN/RCLK/SCK".
			Changed references of "RDCFGN" to "TSALLN".
			Changed references of "TDO/RDDATA" to "TDO".
		Architecture	Updated text in Ripple Mode section.
			Added information to Global Set/Reset.
			Added information for Spread Spectrum Clocking
			Modified information for PLL/DLL Cascading. DLL to PLL is now supported.
			Modified AIL Block text and figure.
			Modified Figure 2-20 DDR/Shift Register Block.
			Added Information to Hot Socketing.
			Added new information for I/O Architecture Rules.
			Added information to SERDES Power Supply Sequencing Requirements.
		DC and Switching Characteristics	Added footnote to Hot Socketing Specifications table.
			Modified Initialization and Standby Supply Current table.
			Modified GSR Timing table.
			Modified sysCLOCK DLL Timing table to include I_{DUTY} .
			Deleted Readback Timing information from sysCONFIG Port Timing table.
			Modified data in External Switching Characteristics table.
		Pin Information	Added information to the Signal Descriptions table for HDC/SI, LDCN/SCS.
			Added footnote to Signal Descriptions table.
			Modified Description for signal BUSYN/RCLK/SCK.
			Modified data in Pin Information Summary and device-specific Pinout Information tables.